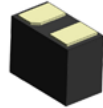


# STN06 1050BL40

## TVS Diode ESD suppressor



### Product features

- Compact package 0.6 mm × 0.3 mm
- Low clamping voltage
- Low capacitance for high speed data lines
- High ESD withstand in low capacitance construction
- Meets moisture sensitivity level (MSL) 3
- Molding compound flammability rating: UL 94V-0
- Termination finish: Ni/Pd/Au

### Applications

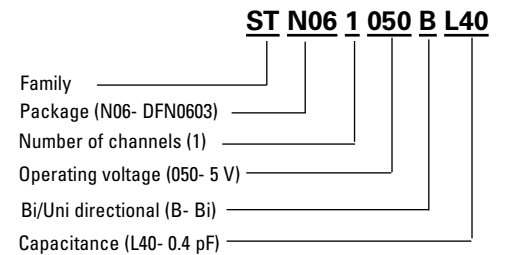
- Cellular handsets and accessories
- Personal digital assistants (PDAs)
- Notebooks, desktops, and servers
- Portable instrumentation
- Communication systems
- Microprocessor based equipment

### Environmental compliance and general specifications

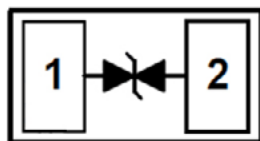
- IEC61000-4-2 (ESD)
  - ±20 kV (air)
  - ±18 kV (contact)
- IEC61000-4-5 (Lightning) 5 A (8/20 μs)



### Ordering part number



### Pin out/functional diagram



DFN0603-2L  
(Bottom view)



Powering Business Worldwide

### Absolute maximum ratings

(+25 °C, RH=45%-75%, unless otherwise noted)

#### STN061050BL40

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20 $\mu$ s waveform	P <sub>pp</sub>	100	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	+/-20	kV
ESD per IEC 61000-4-2 (Contact)		+/-18	
Lead soldering temperature	T <sub>L</sub>	+260 (10 seconds)	°C
Operating junction temperature range	T <sub>J</sub>	-55 to +125	°C
Storage temperature range	T <sub>STG</sub>	-55 to +150	°C

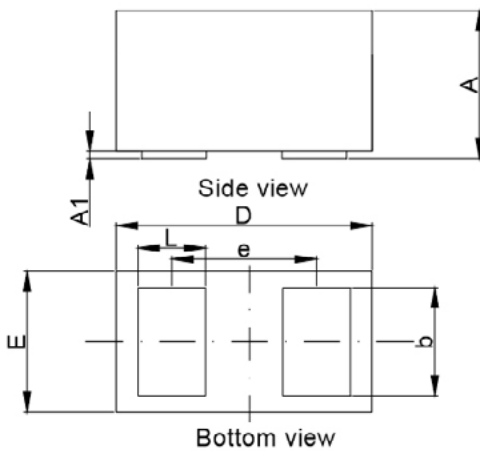
### Electrical characteristics

(+25 °C)

#### STN061050BL40

Parameter	Test condition	Minimum	Typical	Maximum	Symbol (Units)
Reverse working voltage	-	-	-	5.0	V <sub>RWM</sub> (V)
Reverse breakdown voltage	I <sub>T</sub> = 1 mA	6.0	-	10.0	V <sub>BR</sub> (V)
Reverse leakage current	V <sub>RWM</sub> = 5 V	-	-	1	I <sub>R</sub> ( $\mu$ A)
Peak pulse current	t <sub>p</sub> = 8/20 $\mu$ s	-	-	5	I <sub>PP</sub> (A)
Clamping voltage	I <sub>PP</sub> = 1 A, t <sub>p</sub> = 8/20 $\mu$ s	-	12	15	V <sub>C</sub> (V)
	I <sub>PP</sub> = 5 A, t <sub>p</sub> = 8/20 $\mu$ s	-	20	23	V <sub>C</sub> (V)
Junction capacitance	V <sub>RWM</sub> = 0 V, f = 1 MHz	-	0.4	0.6	C <sub>J</sub> (pF)

### Mechanical parameters, pad layout- mm

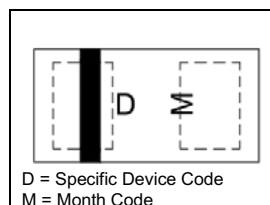


Land pattern

#### Millimeter

Dimension	Minimum	Typical	Maximum
A	0.27	-	0.33
A1	0.00	-	0.025
b	0.21	-	0.29
D	0.56	-	0.66
E	0.28	-	0.35
e	-	0.355	-
L	0.14	-	0.22

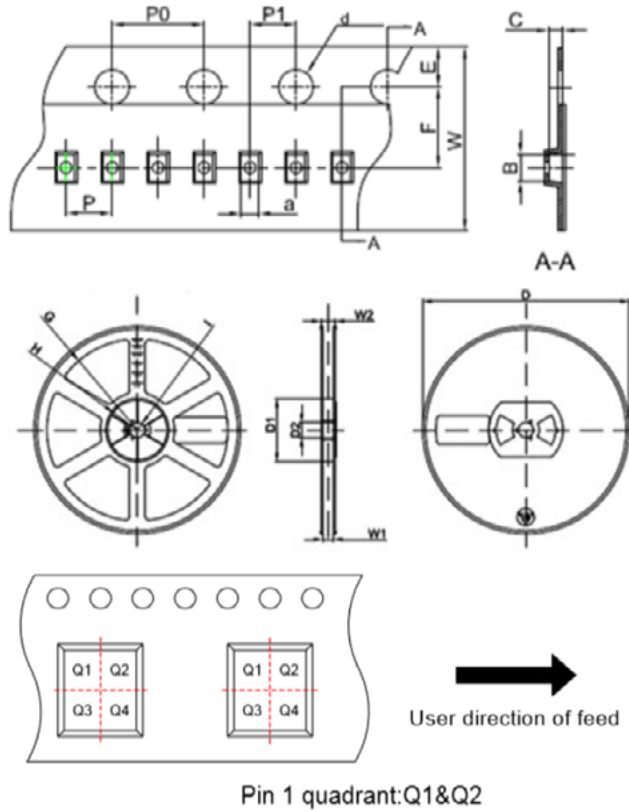
### Part marking



**Packaging information mm/inches**

Drawing not to scale.

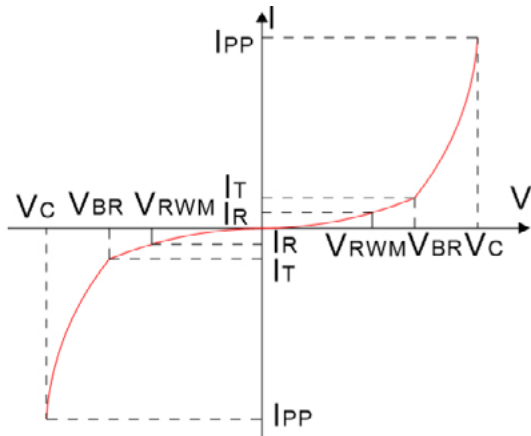
Supplied in tape and reel packaging, 10,000 parts per 7" EIA-481 diameter reel



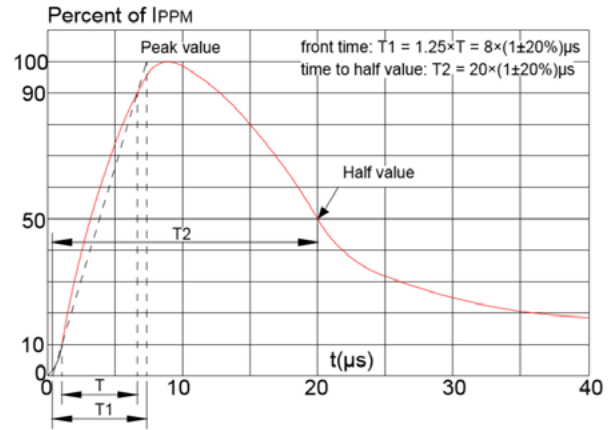
Symbol	Millimeters	Inches
	Typ.	Typ.
a	0.41	0.016
B	0.70	0.028
C	0.38	0.015
d	Φ1.50	Φ0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	2.00	0.079
P1	2.00	0.079
W	8.00	0.315
D	Φ178	Φ7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.00	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

**Ratings and V-I characteristic curves** (+25 °C unless otherwise noted)

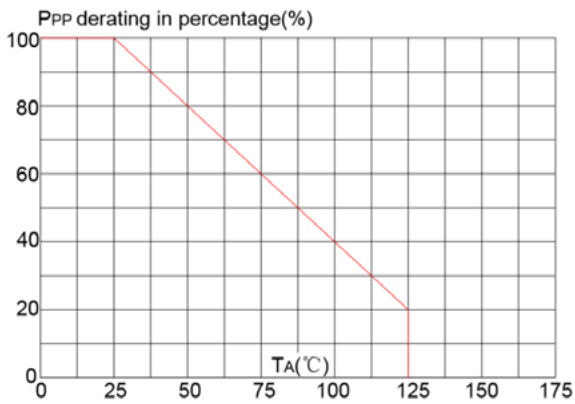
**V- I curve characteristics (Bi-directional)**



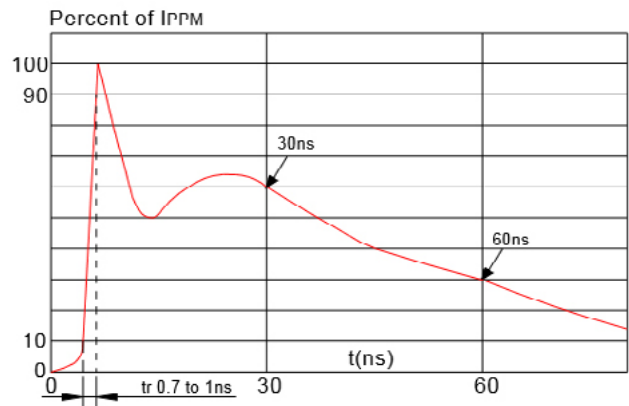
**Pulse waveform (8/20  $\mu$ s)**



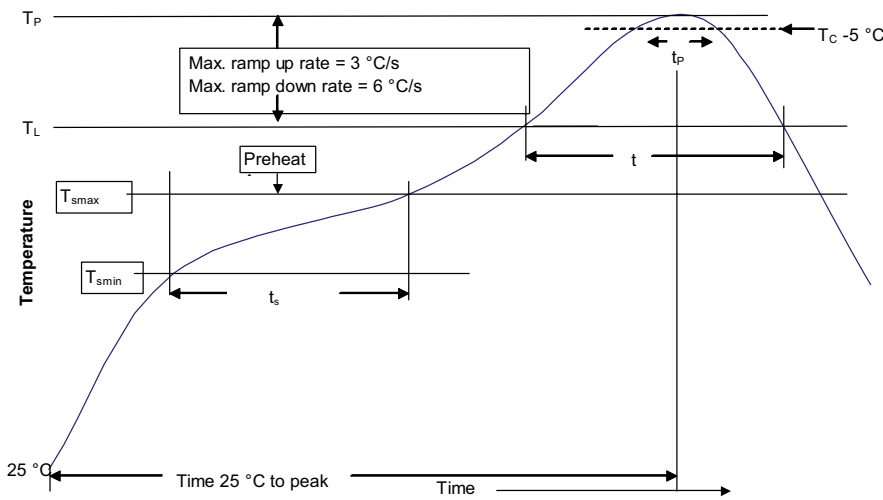
**Pulse derating curve**



**ESD waveform**



**Solder reflow profile**



**Table 1 - Standard SnPb solder ( $T_C$ )**

Package thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ $\geq$ 350
<2.5 mm	235 °C	220 °C
$\geq$ 2.5 mm	220 °C	220 °C

**Table 2 - Lead (Pb) free solder ( $T_C$ )**

Package thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ 350 - 2000	Volume $\text{mm}^3$ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

**Reference J-STD-020**

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak		
• Temperature min. ( $T_{smin}$ )	100 °C	150 °C
• Temperature max. ( $T_{smax}$ )	150 °C	200 °C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Ramp up rate $T_L$ to $T_P$	3 °C/ second max.	3 °C/ second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time ( $t_L$ ) maintained above $T_L$	60-150 seconds	60-150 seconds
Peak package body temperature ( $T_P$ )*	Table 1	Table 2
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_C$ )	20 seconds*	30 seconds*
Ramp-down rate ( $T_P$ to $T_L$ )	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.

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